**Product / Process Change Notice**

**Parts Affected:**

General purpose and ultrafast recovery rectifiers manufactured in the SMA, SMAFL, SMB, SMC, and DO-201 cases.

**Extent of Change:**

Addition of new wafer fab.

**Reason for Change:**

As part of Central Semiconductor’s supply chain risk mitigation initiative, and in an effort to ensure undisrupted product supply, an additional wafer fabrication site is being added for the referenced product families. Product specifications, quality and reliability are not impacted by this addition.

**Effect of Change:**

This addition does not affect the fit, form or function of the devices.

**Qualification:**

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| **Test** | **Condition** | **Duration** | **Failure rate** |
| **Pre Conditioning(P.C) (SMD qualification parts before test T.C., A.C, T.H.B , I.O.L and R.S.H）**  | 1. TCT -55~+150 ℃ ,5 cycle 2. Bake 125 +5/-0 ℃ , 24hours 3. Temperature humidity 85℃/85%RH, 168hours 4. Reflow 3 times  | 1 Cycle | 0/773 Lots  |
| **Temperature Cycling (T.C.)** | TA= -55+0℃/-10℃ 10min(Min) TA= +150+15℃/-0℃ 10min(Min) Transfer time less than 1min. The load should reach temp. within 15min  | 1000 Cycles | 0/773 Lots  |
| **High Temperature Reverse Bias (HTRB)** | TA=140℃, VR=100%VB DC supply  | 1000 Hours | 0/773 Lots  |
| **Resistance to Solder Heat (R.S.H.)** | T =260°C ±5°CDwell time = 10 sec. | 1 Cycle | 0/303 Lots  |
| **Intermittent****Forward****Operation Life (I.O.L.)** | I=1.0 × IF DC supply On time: 2mins at least, Off time: 2mins at least  | 15,000 Cycles | 0/773 Lots  |
| **Autoclave (A.C.)** | Temperature = 121°C ± 2°C; relative humidity = 100%; vapor pressure = 29.7 psia (15psig) | 96 Hours | 0/773 Lots  |
| **High Humidity High Temperature Reverse Bias (H3TRB)** | TA=85℃+/-2℃ RH=85%+/-5% VR=80%VB(customer spec.) DC Supply  | 1000 Hours | 0/773 Lots  |

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| **Test** | **Condition** | **Duration** | **Failure rate** |
| **Solderability (SD)**  | Temperature of solder Pb free: POT=245±5℃ Solder immersion time=5±0.5 sec Dipping depth= within 1.27mm of the body.  | 1 Cycle | 0/103 Lots  |
| **ESD - HBM** |  100 pF / 1.5 KΩ  | 3 Cycles | 0/303 Lots |
| **ESD - MM** | 200pF / 0Ω  | 3 Cycles | 0/303 Lots  |

**Effective Date of Change:**

Existing inventory will be shipped until depleted.

**Sample Availability:**

Please contact your salesperson or manufacturer’s representative for samples.

**Part Numbers Affected:**



As per JEDEC standard JESD46, Customer Notification of Product/Process Changes by Solid-State Suppliers, a lack of acknowledgement of a PCN within thirty (30) days constitutes acceptance of the change.

The undersigned acknowledges and accepts Central Semiconductor’s Product/Process Change Notification (PCN).

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| Company Name: |  |
| Address: |  |
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| Printed Name: |  |
| Title: |  |
| Signature: |  |
| Date: |  |